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(54) RESIN COMPOSITION FOR IN-MOLD COATING MOLDING AND PROCESS FOR IN-MOLD COATING MOLDING

(57)Abstract:

PURPOSE: To obtain a coated molding good in adhesion of the coating layer in an in-mold coating molding process.

CONSTITUTION: The resin composition for in-mold coating molding molding material and a thermosetting coating material one of which is a thermosetting resin composition comprising a thermosetting resin and an unsaturated isocyanate or an unsaturated isothiocyanate, and the other of which comprises a thermosetting resin and at least one member selected from among a compound containing a copolymerizable double bond and a hydroxyl group in the molecule, an unsaturated carboxylic acid, an unsaturated sulfonic acid, an unsaturated phosphoric acid and an unsaturated mercaptan.

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